

**N-Ch MOSFET** 

# **General Description**

The WSK290N04G6 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSK290N04G6 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

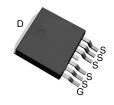
### **Product Summery**

BVDSS	RDSON	ID
40V	1.2mΩ	290A

# **Applications**

- Switching application
- Power Management for Inverter Systems.

# **TO-263-6L Pin Configuration**





# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit		
Common F	Ratings (T <sub>C</sub> =25°C Unless Otherwise Noted)				
V <sub>DSS</sub>	Drain-Source Voltage		40	V	
V <sub>GSS</sub>	Gate-Source Voltage		±20		
TJ	Maximum Junction Temperature		175	℃	
T <sub>STG</sub>	Storage Temperature Range	-55 to 175	℃		
Is	Diode Continuous Forward Current	T <sub>C</sub> =25℃	190	А	
Mounted o	n Large Heat Sink	•		•	
I <sub>DM</sub>	Pulsed Drain Current <sup>1</sup>	T <sub>C</sub> =25℃	1015	А	
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> =25℃	290	A	
		T <sub>C</sub> =100°C	207		
P <sub>D</sub>	Maximum Dawar Dissination	T <sub>C</sub> =25℃	230	W	
	Maximum Power Dissipation	T <sub>C</sub> =100°C	115		
$R_{\theta JC}$	Thermal Resistance-Junction to Case		0.65	°C/\\/	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	50	— °C/W		
Avalanche	Ratings		•	•	
E <sub>AS</sub>	Avalanche Energy, Single Pulsed	L=0.5mH	1400	mJ	

NOTE:

1,Pulse width limited by maximum junction temperature.

2,UIS tested and pulse width limited by maximum junction temperature (initial temperature Tj=25°C.



# Electrical Characteristics (T<sub>J</sub>=25 ℃, unless otherwise noted)

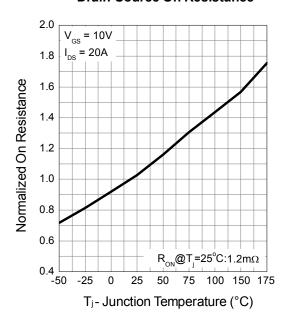
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Static Char	racteristics		ļ	!		
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA	40	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V	-	-	1	
		T <sub>J</sub> =85℃	-	-	10	μΑ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_{DS}=250\mu A$	1.0	1.8	2.5	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
R <sub>DS(ON)</sub> *	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =30A	-	1.2	1.6	mΩ
R <sub>DS(ON)</sub> *	Drain-Source On-state Resistance	V <sub>GS</sub> =4.5V, I <sub>DS</sub> =20A	-	1.5	2.5	mΩ
Diode Cha	racteristics	•	•			
V <sub>SD</sub> *	Diode Forward Voltage	I <sub>SD</sub> =20A, V <sub>GS</sub> =0V	-	0.8	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	$I_{SD}$ =104A, $dI_{SD}$ /	-	45	-	ns
$Q_{rr}$	Reverse Recovery Charge	dt=100A/μs	-	98	-	nC
Dynamic C	haracteristics					
$R_{G}$	Gate Resistance	V <sub>GS</sub> =0V,V <sub>DS</sub> =0V,F=1MHz	-	1.0	-	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V,	-	8102	-	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =20V,	-	945	-	
$C_{rss}$	Reverse Transfer Capacitance	Frequency=1.0MHz	-	410	-	
t <sub>d(ON)</sub>	Turn-on Delay Time		-	29	-	ns ns
T <sub>r</sub>	Turn-on Rise Time	$V_{DD}$ =20V, R <sub>G</sub> =6 $\Omega$ , $I_{DS}$ =20A, $V_{GS}$ =10V .,	-	17	-	
t <sub>d(OFF)</sub>	Turn-off Delay Time		-	150	-	
T <sub>f</sub>	Turn-off Fall Time		-	65	-	
Gate Charg	ge Characteristics					
$Q_g$	Total Gate Charge		-	142	-	nC
$Q_{gs}$	Gate-Source Charge	V <sub>DS</sub> =20V, V <sub>GS</sub> =10V, I <sub>DS</sub> =20A	-	34	-	
$Q_{gd}$	Gate-Drain Charge		-	25	-	

Note \* : Pulse test ; pulse width  $\leq$ 300 $\mu$ s, duty cycle  $\leq$ 2%.

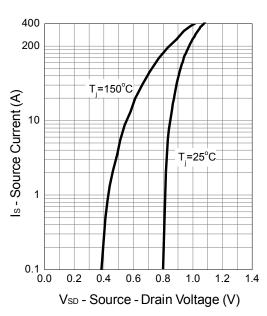


### **Typical Characteristics**

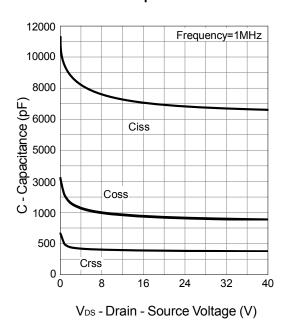
# **Drain-Source On Resistance**



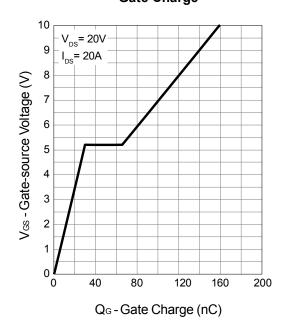
### **Source-Drain Diode Forward**



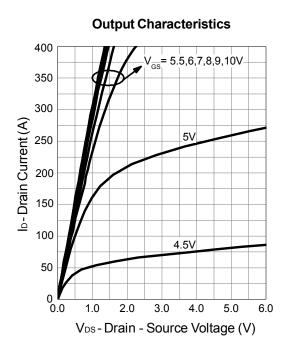
# Capacitance

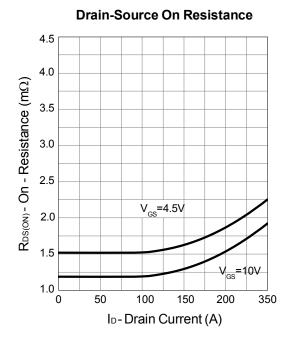


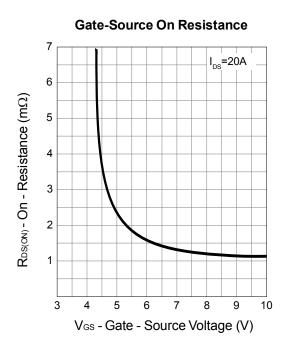
# **Gate Charge**

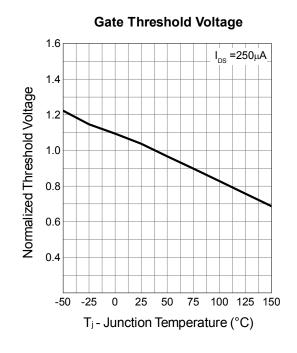




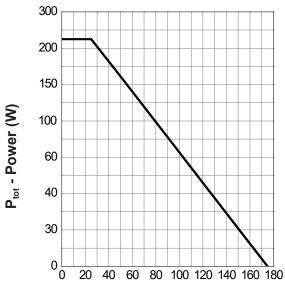








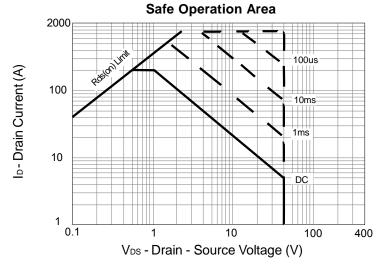




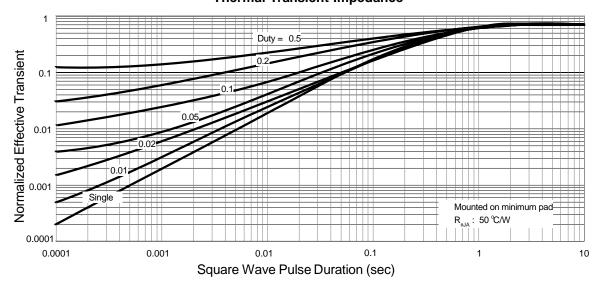
290 250 250 190 90 50 V<sub>G</sub>=10V 0 20 40 60 80 100 120 140 160 180

T<sub>c</sub> - Case Temperature (°C)

T<sub>c</sub> - Case Temperature (°C)



# **Thermal Transient Impedance**





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